

NPN SILICON EPITAXIAL TRANSISTOR (DARLINGTON CONNECTION) FOR LOW-FREQUENCY POWER AMPLIFIERS AND LOW-SPEED SWITCHING

The 2SD2217 is a mold power transistor developed for lowfrequency power amplifiers and low-speed switching. This transistor is ideal for direct driving from the IC out to drivers such as pulse motor drivers and relay drivers in OA and FA equipment.

PACKAGE DRAWING (UNIT: mm)

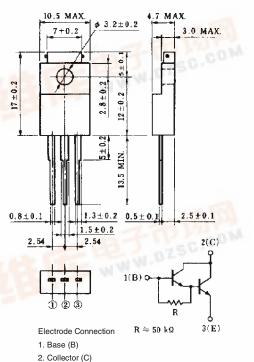
QUALITY GRADES

Standard

Please refer to "Quality Grades on NEC Semiconductor Devices" (Document No. C11531E) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

Parameter	Symbol	Ratings	Unit	
Collector to base voltage	Vсво	300	V	
Collector to emitter voltage	VCEO	300	V	
Emitter to base voltage	Vebo	7	V	
Collector current	IC(DC)	300	mA	
Collector current	IC(pulse)*	600	mA	
Base current	IB(DC)	30	mA	
Total power dissipation	P⊤ (Tc = 25°C)	25	W	
Total power dissipation	P⊤ (Ta = 25°C)	2.0	W	
Junction temperature	Tj	150	°C	
Storage temperature	Tstg	–55 to +150	°C	

ABSOLUTE MAXIMUM RATINGS (Ta = 25°C)



3. Emitter (E)

* PW \leq 10 ms, duty cycle \leq 50%



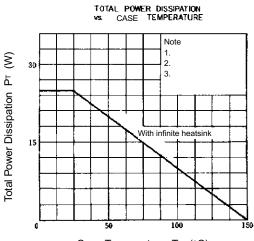
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Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Collector cutoff current	Ісво	Vсв = 300 V, IE = 0			10	μA
Collector cutoff current	ICEO	V _{CE} = 60 V, R _{BE} = ∞			10	μA
Emitter cutoff current	Іево	V _{EB} = 5 V, I _C = 0			10	μA
DC current gain	hfe1**	Vce = 1.5 V, lc = 20 mA	1,000			
DC current gain	hfe2**	Vce = 1.5 V, lc = 100 mA	1,500	7,000	30,000	
Collector saturation voltage	V _{CE(sat)} **	Ic = 100 mA, I _B = 0.2 mA		0.8	1.5	V
Base saturation voltage	VBE(sat)**	Ic = 100 mA, I _B = 0.2 mA		1.4	2.0	V
Gain bandwidth product	f⊤	Vce = 1.5 V, Ic = 20 mA		45		MHz
Collector capacitance	Cob	V_{CB} = 10 V, I _E = 0, f = 1.0 MHz		22		pF

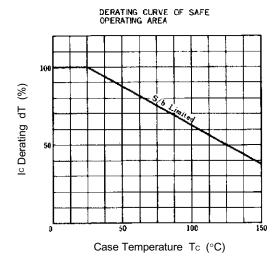
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

** Pulse test PW \leq 350 μ s, duty cycle \leq 2%

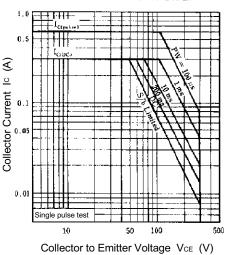
TYPICAL CHARACTERISTICS (Ta = 25°C)



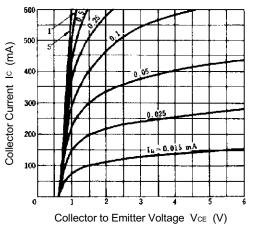
Case Temperature Tc (°C)

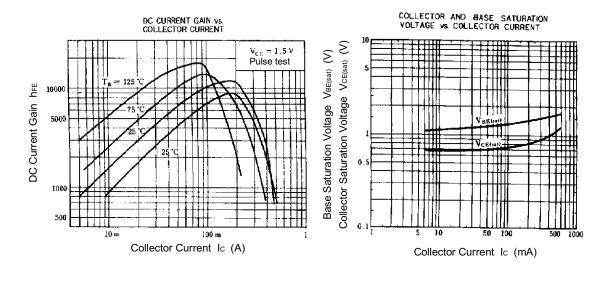


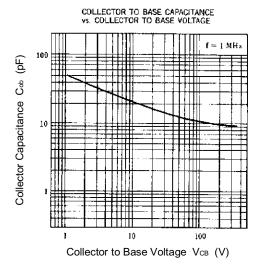
FORWARD BIAS SAFE OPFRATING AREA



COLLECTOR CURRENT VS. COLLECTOR TO EMITTER VOLTAGE







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